



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **K1208-01** DATE: **September 11, 2012**
 Product Affected: 9FG104C
 9FG104D
 9FG108C
 9FG108D
 Date Effective: **December 11, 2012**

MEANS OF DISTINGUISHING CHANGED DEVICES:
 Product Mark New Ordering Part#
 Back Mark
 Date Code
 Other

Contact: Bimla Paul
 Title: Product Quality Assurance Attachment: Yes No
 Phone #: (408) 574-6419
 Fax #: (408) 284-8362 Samples: Contact your local sales representative for
 E-mail: Bimla.Paul@idt.com sample and datasheet requests.

DESCRIPTION AND PURPOSE OF CHANGE:

- | | |
|--|---|
| <input type="checkbox"/> Die Technology
<input type="checkbox"/> Wafer Fabrication Process
<input type="checkbox"/> Assembly Process
<input type="checkbox"/> Equipment
<input type="checkbox"/> Material
<input type="checkbox"/> Testing
<input type="checkbox"/> Manufacturing Site
<input type="checkbox"/> Data Sheet
<input checked="" type="checkbox"/> Other - Die revision (New Ordering Part#) | This notification is to advise our customers that IDT has made a metal-layer only die revision to the devices mentioned above. This die revision improves production yield of the devices. IDT will be discontinuing the Rev C and Rev D devices and is asking customers to qualify the Rev E devices and switch to this revision. Rev E has the same performance as Rev D and much improved performance over the Rev C. The orderable part numbers have changed to indicate the Rev E. |
|--|---|

RELIABILITY/QUALIFICATION SUMMARY:

There is no expected change to the product quality or reliability performance.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
 IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ *Approval for shipments prior to effective date.*
 Name/Date: _____ E-Mail Address: _____
 Title: _____ Phone # /Fax #: _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT I - PCN #: K1208-01

PCN Type: Die Revision Change

Data Sheet Change: Yes

Detail of Change:

This notification is to advise our customers that IDT has made a metal-layer only die revision to the devices mentioned above. This die revision improves production yield of the devices. IDT will be discontinuing the Rev C and Rev D devices and is asking customers to qualify the Rev E devices and switch to this revision. Rev E has the same performance as Rev D and much improved performance over the Rev C. The orderable part numbers have changed to indicate the Rev E as shown in Table 1.

Table 1

Existing Ordering Part#	New Ordering Part#
9FG104CFLF	9FG104EFLF
9FG104CFLFT	9FG104EFLFT
9FG104CGLF	9FG104EGLF
9FG104CGLFT	9FG104EGLFT
9FG104DFILF	9FG104EFILF
9FG104DFILFT	9FG104EFILFT
9FG104DFLF	9FG104EFLF
9FG104DFLFT	9FG104EFLFT
9FG104DGILF	9FG104EGILF
9FG104DGILFT	9FG104EGILFT
9FG104DGLF	9FG104EGLF
9FG104DGLFT	9FG104EGLFT
9FG108CFLF	9FG108EFLF
9FG108CFLFT	9FG108EFLFT
9FG108CGLF	9FG108EGLF
9FG108CGLFT	9FG108EGLFT
9FG108DFILF	9FG108EFILF
9FG108DFILFT	9FG108EFILFT
9FG108DFLF	9FG108EFLF
9FG108DFLFT	9FG108EFLFT
9FG108DGILF	9FG108EGILF
9FG108DGILFT	9FG108EGILFT
9FG108DGLF	9FG108EGLF
9FG108DGLFT	9FG108EGLFT

There is no change in die technology/process. Samples are available for customer evaluation upon request.



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ATTACHMENT I - PCN #: K1208-01

Qualification Test Plan and Result:

Product: 9FG108EGILF

Foundry: Global Foundries

Technology Information: CMOS 0.35 μ m

Report Date: June 12, 2012

Device Qual Test Results Summary

Test Description	Conditions	Sample Size	Rejects	Comments
ESD: Human Body Model	JS-001	3	0	2000V
ESD: Charged Device Model	JESD22-C101	3	0	500V
Latch-Up	JESD78	6	0	
Electrical Characterization	Per Datasheet	10*	-	Passed

Note: * Sample size applies to base characterization

Qualification Test Result Summary – JESD47 Recommended Tests

Test /Conditions	Conditions	Sample Size	Rejects	Comments
High Temperature Operating Life (Dynamic)	JESD22-A108D, +125°C, Vccmax @ 1000 hours or equivalent	77	0	
		77	0	
		77	0	
Temperature Cycle	JESD22-A104D, -55°C to +125°C, 700 cycles	25	0	
		25	0	
		25	0	
High Temperature Storage Bake	JESD22-A-103D, 150°C, 1000 hrs	25	0	
		25	0	
		25	0	
Highly Accelerated Stress Test (HAST)	EIA/JESD22-A110D, 130°C/85%R.H. Vcc max for 100 hours.	25	0	
		25	0	
		25	0	
Ball Shear Test	JESD22-B116A, Ball Shear Strength	5	0	

Note: For HAST and Temperature Cycle, samples have been subjected to pre-conditioning per JESD22-A113